

## Solder Paste No-Clean Sn42/Bi57.6/Ag0.4 60g T4 Mesh Two Part Mix™ [PATENT PENDING]

### Product Highlights

2 year shelf life unrefrigerated before mixed  
Printing speeds up to 100mm/sec  
Long stencil life  
Wide process window

Clear residue  
Low voiding  
Excellent wetting compatibility on most board finishes  
RoHS II and REACH compliant

### Specifications

|                      |   |
|----------------------|---|
| Alloy:               | Sn42/Bi57.6/Ag0.4   |
| Mesh Size:           | T4  |
| Micron (µm) Range:   | 20-38   |
| Flux Type:           | Synthetic No-Clean  |
| Flux Classification: | RELO  |
| Metal Load:          | 87% Metal by Weight   |
| Melting Point:       | 138°C (281°F)   |
| Packaging:           | 2 compartment bag, includes Jar for after mixed storage, 60g  |
| Shelf Life:          | Before Mixed: Refrigerated >24 months, Unrefrigerated >24 months<br>After Mixed: Refrigerated >6 months, Unrefrigerated >2 months |

### How to Mix the Two Parts

This product **MUST BE MIXED** within its bag before use. To mix, squeeze the flux pocket towards the solder powder pocket and the seal between the two compartments will break open, creating a single pocket bag. Then knead the mixture back and forth for 2-3 minutes, or until a uniform consistency is achieved.

### Printer Operation

Print Speed: 25-100mm/sec  
Squeegee Pressure: 70-250g/cm of blade  
Under Stencil Wipe: Once every 10-25 prints, or as necessary

### Stencil Life

>8 hours @ 20-50% RH 22-28°C (72-82°F)  
>4 hours @ 50-70% RH 22-28°C (72-82°F)

### Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

### Storage and Handling

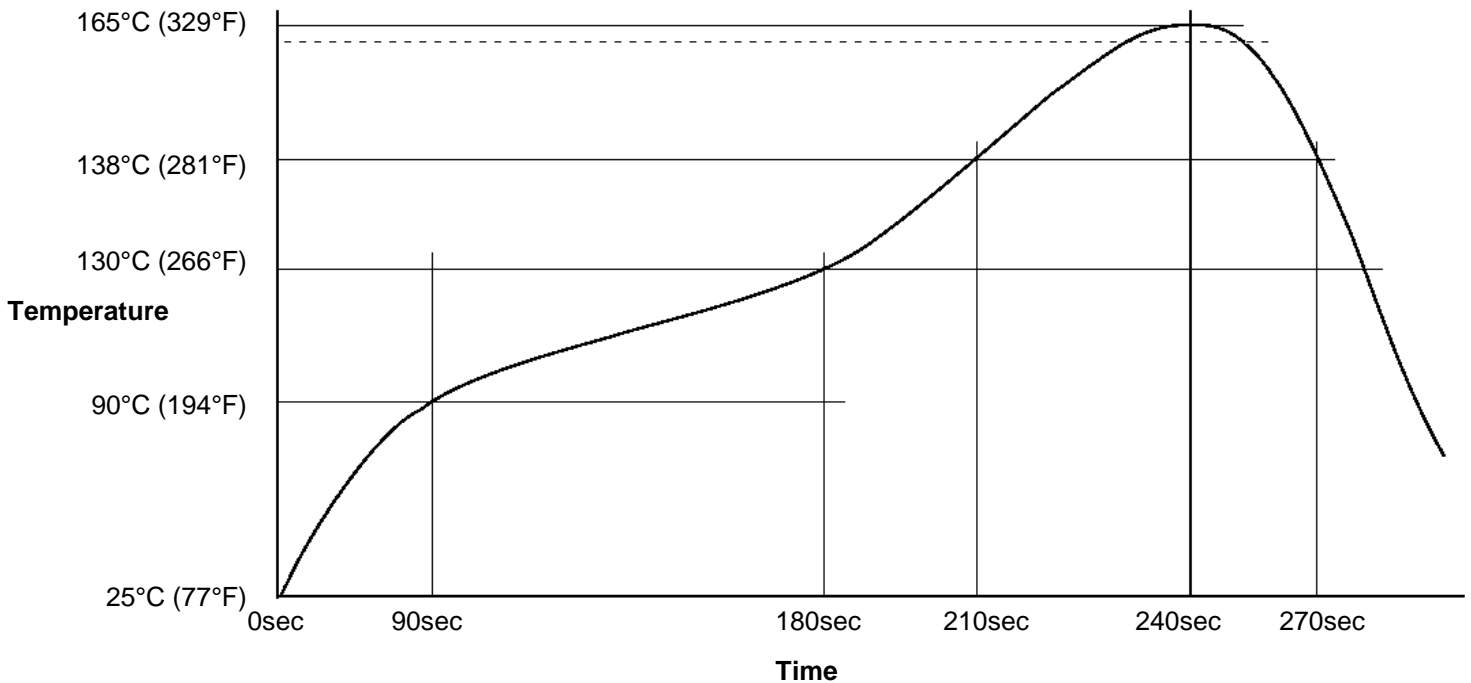
Before Mixed: Store refrigerated or at room temperature 3-25°C (37-77°F). Do not freeze.  
After Mixed: Refrigerate at 3-8°C (37-46°F). Do not freeze. Allow 4 hours for solder paste to reach an operating temperature of 20-25°C (68-77°F) before use. Once mixed, the solder paste can be dispensed by cutting a small corner off the bag. It can be resealed with a piece of Scotch® tape, or it can be stored by dispensing the entire bag into the provided empty jar.

### Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Recommended Profile

Reflow profile for Sn42/Bi57.6/Ag0.4 solder assembly, designed as a starting point for process optimization.



Test Results

| Test J-STD-004 or other requirements as stated            | Test Requirement                                   | Result   |
|---|--|--|
| Copper Mirror   | IPC-TM-650: 2.3.32                                 | L: No breakthrough   |
| Corrosion   | IPC-TM-650: 2.6.15                                 | L: No corrosion  |
| Quantitative Halides                                      | IPC-TM-650: 2.3.28.1                               | L: <0.5%   |
| Electrochemical Migration                                 | IPC-TM-650: 2.6.14.1                               | L: <1 decade drop (No-clean)   |
| Surface Insulation Resistance 85°C, 85% RH @ 168 Hours    | IPC-TM-650: 2.6.3.7                                | L: ≥100MΩ (No-clean)   |
| Tack Value  | IPC-TM-650: 2.4.44                                 | 48g  |
| Viscosity – Malcom @ 10 RPM/25°C (x10 <sup>3</sup> mPa/s) | IPC-TM-650: 2.4.34.4                               | Print: 125-180, Dispense: 90-130   |
| Visual  | IPC-TM-650: 3.4.2.5                                | Clear and free from precipitation  |
| Conflict Minerals Compliance                              | Electronic Industry Citizenship Coalition (EICC)   | Compliant  |
| REACH Compliance  | Articles 33 and 67 of Regulation (EC) No 1907/2006 | Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials |

Conforms to the following Industry Standards:

|   |     |
|---|-----|
| J-STD-004B, Amendment 1 (Solder Fluxes):                                    | Yes |
| J-STD-005A (Solder Pastes):   | Yes |
| J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): | Yes |
| RoHS 2 Directive 2011/65/EU:  | Yes |

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